

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
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CHIEN-HUA CHEN	11/15/2018
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PROPERTY NUMBERS Total: 1	
Property Type	Number
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NAME OF SUBMITTER:	WESLEY L. AUSTIN
SIGNATURE:	/Wesley L. Austin/
DATE SIGNED:	05/29/2020
Total Attachments: 2	
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source=85887989-Assignment#page2.tif	

HP Inc.
3390 E. Harmony Road
Mail Stop 35
Fort Collins, Colorado 80528

PATENT APPLICATION

RECORD ID: 85005946

ASSIGNMENT OF PATENT APPLICATION

I, the undersigned, for good and valuable consideration, the receipt of which is hereby acknowledged, agree to assign and transfer and hereby assign and transfer to HEWLETT-PACKARD DEVELOPMENT COMPANY, L.P., a Texas Limited Partnership having its principal place of business in Houston, Texas, (hereinafter "HPDC"), its successors, and its assigns, my entire right, title, and interest, including all rights of priority, in, to, and under an application for patent entitled (English-language title in parentheses if said application for patent is in another language):

TWO-STEP MOLDING FOR A LEAD FRAME

Filing Date: 16 November 2018 Application No.: PCT/US2018/061597 Patent Office: US

the subject matter, including any and all inventions, improvements, and discoveries, set forth in said application for patent (as used herein "patent" refers to any form of intellectual property protection including, without limitation, invention rights, utility patent rights, design rights, and utility model rights) (hereinafter "inventions"); any and all existing and future applications for patent of any country or region or under any international agreement for any of said inventions (including, without limitation, said application for patent, any and all applications for patent directly or indirectly claiming priority to or benefit of any application for patent for any of said inventions, any and all applications for patent from which any application for patent for any of said inventions directly or indirectly claims priority or benefit, and any and all continuation applications of, continuation-in-part applications (hereinafter CIPs) of, divisional applications of, national-phase applications of, regional-phase applications of, renewals of, and substitutes for any application for patent for any of said inventions) (hereinafter "Applications for Patent"); any and all patents which may be granted on or as a result of said Applications for Patent (hereinafter "Patents"); and any and all reissues, reexaminations, and extensions of said Applications for Patent or said Patents.

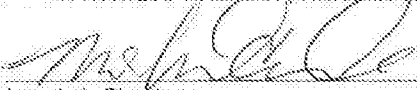
I HEREBY represent that I convey my full rights in all countries and regions and under all international agreements to the entire right, title, and interest herein assigned and transferred, and that I have not executed and will not execute any agreement in conflict herewith;

AND I HEREBY authorize HPDC, its successors, its assigns, its nominees, and its legal representatives to file said Applications for Patent in its name or in my name in any country or region or under any international agreement, and further authorize HPDC, its successors, its assigns, its nominees, and its legal representatives to insert the filing date, application number, and patent office of said application for patent, now identified by the Record ID and title set forth above, when known to them;

AND I HEREBY authorize and request the officials of all countries and regions and under all international agreements whose duty it is to issue patents, to issue to HPDC, its successors, or its assigns, as assignee of my entire right, title, and interest, said Patents, in accordance with the terms of this assignment and transfer;

AND I HEREBY covenant and agree that I will, each time a request is made, and without undue delay, execute and deliver all such papers as may be necessary or desirable to perfect the title in said inventions, Applications for Patent, and Patents, to HPDC, its successors, or its assigns; communicate to HPDC, its successors, its assigns, its nominees, or its legal representatives, all known facts respecting said inventions, Applications for Patent, and Patents; testify in any legal or administrative proceedings and sign all lawful papers (including, without limitation, divisional applications, continuation applications, CIPs, and reissue applications) relating to said inventions, Applications for Patent, and Patents; and make all rightful oaths and declarations and generally to do everything possible to aid HPDC, its successors, its assigns, its nominees, and its legal representatives to obtain, maintain, and enforce, for its or their own benefit, proper intellectual property protection for said inventions, Applications for Patent, and Patents, provided the expenses which may be incurred by me in lending such cooperation and assistance are paid by HPDC, its successors, its assigns, its nominees, or its legal representatives.

IN WITNESS WHEREOF, I hereunto set my hand and seal:


Inventor's Signature

15 Nov 2018
Day Month Year

Michael W Cumble
Given (First and Middle) Name(s) Family Name

HP Inc.
3390 E. Harmony Road
Mail Stop 35
Fort Collins, Colorado 80528

PATENT APPLICATION

RECORD ID: 85005946

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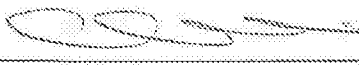
I HEREBY represent that I convey my full rights in all countries and regions and under all international agreements to the entire right, title, and interest herein assigned and transferred, and that I have not executed and will not execute any agreement in conflict herewith;

AND I HEREBY authorize HPDC, its successors, its assigns, its nominees, and its legal representatives to file said Applications for Patent in its name or in my name in any country or region or under any international agreement; and further authorize HPDC, its successors, its assigns, its nominees, and its legal representatives to insert the filing date, application number, and patent office of said application for patent, now identified by the Record ID and title set forth above, when known to them;

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AND I HEREBY covenant and agree that I will, each time a request is made, and without undue delay, execute and deliver all such papers as may be necessary or desirable to perfect the title in said Inventions, Applications for Patent, and Patents, to HPDC, its successors, or its assigns; communicate to HPDC, its successors, its assigns, its nominees, or its legal representatives, all known facts respecting said Inventions, Applications for Patent, and Patents; testify in any legal or administrative proceedings and sign all lawful papers (including, without limitation, divisional applications, continuation applications, CIPs, and reissue applications) relating to said Inventions, Applications for Patent, and Patents; and make all rightful oaths and declarations and generally to do everything possible to aid HPDC, its successors, its assigns, its nominees, and its legal representatives to obtain, maintain, and enforce, for its or their own benefit, proper intellectual property protection for said Inventions, Applications for Patent, and Patents, provided the expenses which may be incurred by me in lending such cooperation and assistance are paid by HPDC, its successors, its assigns, its nominees, or its legal representatives.

IN WITNESS WHEREOF, I hereunto set my hand and seal:



Inventor's Signature
Chien-Hua Chen

Given (First and Middle) Name(s) Family Name

15 11 2018
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